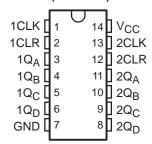
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Dual 4-Bit Binary Counters With Individual Clocks
- Direct Clear for Each 4-Bit Counter
- Can Significantly Improve System
 Densities by Reducing Counter Package
 Count by 50 Percent

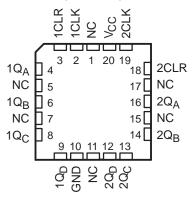
description/ordering information

The 'HC393 devices contain eight flip-flops and additional gating to implement two individual 4-bit counters in a single package. These devices comprise two independent 4-bit binary counters, each having a clear (CLR) and a clock (CLK) input. N-bit binary counters can be implemented with each package, providing the capability of divide by 256. The 'HC393 devices have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system timing signals.

SN54HC393 . . . J OR W PACKAGE SN74HC393 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HC393 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

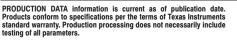
ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC393N	SN74HC393N
		Tube of 50	SN74HC393D	
	SOIC - D	Reel of 2500	SN74HC393DR	HC393
		Reel of 250	SN74HC393DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC393NSR	HC393
	SSOP - DB	Reel of 2000	SN74HC393DBR	HC393
		Tube of 90	SN74HC393PW	
	TSSOP - PW	Reel of 2000	SN74HC393PWR	HC393
		Reel of 250	SN74HC393PWT	
	CDIP – J	Tube of 25	SNJ54HC393J	SNJ54HC393J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC393W	SNJ54HC393W
	LCCC - FK	Tube of 55	SNJ54HC393FK	SNJ54HC393FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

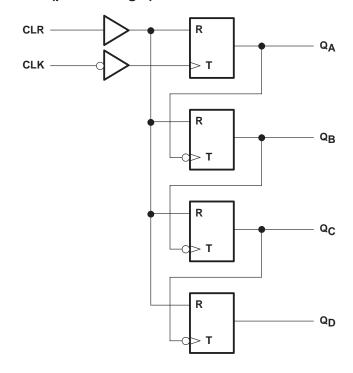




FUNCTION TABLE COUNT SEQUENCE (each counter)

COLINIT		OUTI	PUTS	
COUNT	Q_{D}	QC	Q_{B}	Q_{A}
0	L	L	L	L
1	L	L	L	Н
2	L	L	Н	L
3	L	L	Н	Н
4	L	Н	L	L
5	L	Н	L	Н
6	L	Н	Н	L
7	L	Н	Н	Н
8	Н	L	L	L
9	Н	L	L	Н
10	Н	L	Н	L
11	Н	L	Н	Н
12	Н	Н	L	L
13	Н	Н	L	Н
14	Н	Н	Н	L
15	Н	Н	Н	Н

logic diagram, each counter (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	c) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{sto}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	154HC39	3	SN	174HC39	3	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δv†	Input transition rise/fall time	$V_{CC} = 4.5 \text{ V}$			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[†] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SN54HC393, SN74HC393 DUAL 4-BIT BINARY COUNTERS

SCLS143D - DECEMBER 1982 - REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	NIDITIONS	.,	Т	A = 25°C	;	SN54F	IC393	SN74H	C393	
PARAMETER	TEST CC	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Vон	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VoL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	·	6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci		_	2 V to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			\ ,	T _A = 1	25°C	SN54H	C393	SN74H	IC393	
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		28	
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		
١.	Delega demotion		6 V	14		20		18		
t _W	Pulse duration		2 V	80		120		100		ns
		CLR high	4.5 V	16		24		20		
			6 V	14		20		18		
			2 V	25		25		25		
t _{su}	Setup time, CLR inactive		4.5 V	5		5		5		ns
			6 V	5		5		5		

SN54HC393, SN74HC393 DUAL 4-BIT BINARY COUNTERS

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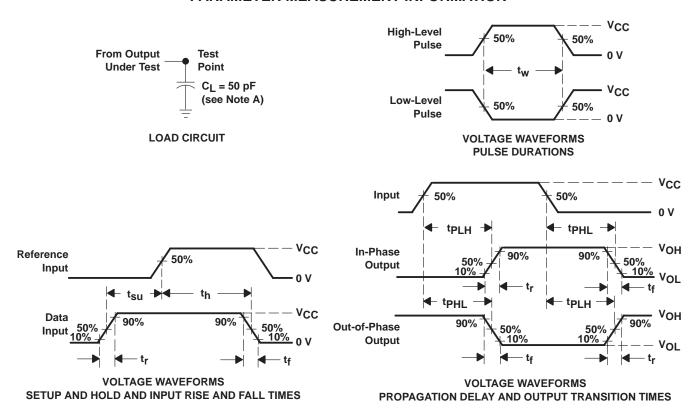
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то		T,	Δ = 25°C	;	SN54H	IC393	SN74H	IC393	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	10		4.2		5		
f _{max}	CLK	Q_A	4.5 V	31	50		21		25		MHz
			6 V	36	60		25		28		
			2 V		50	120		180		150	
		QA	4.5 V		15	24		36		30	
			6 V		13	20		31		26	
			2 V		72	190		285		240	
		QB	4.5 V		22	38		57		47	
	OL K		6 V		18	32		48		40	
t _{pd}	CLK		2 V		91	240		360		300	ns
		QC	4.5 V		28	48		72		60	
			6 V		22	41		61		51	
			2 V		100	290		430		360	
		Q_{D}	4.5 V		32	58		87		72	
			6 V		24	50		74		62	
			2 V		45	165		250		205	
t _{PHL}	CLR	Any	4.5 V		17	33		49		41	ns
			6 V		14	28		42		35	
			2 V		28	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per counter	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84100012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84100012A SNJ54HC 393FK	Samples
8410001CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8410001CA SNJ54HC393J	Samples
8410001DA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8410001DA SNJ54HC393W	Samples
JM38510/66309BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 66309BCA	Samples
M38510/66309BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 66309BCA	Samples
SN54HC393J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC393J	Samples
SN74HC393D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393DT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC393N	Samples
SN74HC393NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SN74HC393PWT	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC393	Samples
SNJ54HC393FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84100012A SNJ54HC 393FK	Samples
SNJ54HC393J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8410001CA SNJ54HC393J	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SNJ54HC393W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8410001DA SNJ54HC393W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL. Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC393, SN74HC393:

PACKAGE OPTION ADDENDUM

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Catalog : SN74HC393

• Military : SN54HC393

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC393DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74HC393DR	SOIC	D	14	2500	330.0	16.4	6.6	9.3	2.1	8.0	16.0	Q1
SN74HC393DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC393DT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC393NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC393NSR	so	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HC393PWR	TSSOP	PW	14	2000	330.0	12.4	6.85	5.45	1.6	8.0	12.0	Q1
SN74HC393PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC393PWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

7 ili dilliciololio die fiorilliai							
Device	Package Type	Package Drawing	Pins SPQ Length (mm)		Width (mm)	Height (mm)	
SN74HC393DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74HC393DR	SOIC	D	14	2500	366.0	364.0	50.0
SN74HC393DR	SOIC	D	14	2500	340.5	336.1	32.0
SN74HC393DT	SOIC	D	14	250	210.0	210.0 185.0	
SN74HC393NSR	so	NS	14	2000	367.0	367.0	38.0
SN74HC393NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74HC393PWR	TSSOP	PW	14	2000	366.0	364.0	50.0
SN74HC393PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HC393PWT	TSSOP	PW	14	250	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 16-Mar-2023

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
84100012A	FK	LCCC	20	1	506.98	12.06	2030	NA
8410001DA	W	CFP	14	1	506.98	26.16	6220	NA
SN74HC393D	D	SOIC	14	50	506.6	8	3940	4.32
SN74HC393D	D	SOIC	14	50	507	8	3940	4.32
SN74HC393N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HC393N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HC393PW	PW	TSSOP	14	90	530	10.2	3600	3.5
SNJ54HC393FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54HC393W	W	CFP	14	1	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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